

Product Change Notification / GBNG-09WNNA526

Date:

19-Feb-2023

Product Category:

Smart Energy SOC

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5001 Final Notice: Qualification of G700LA as a new mold compound material for selected Atmel ATSENSE201 and ATSENSE301 device families available in 32L TQFP (7x7x1mm) package assembled at ASCL assembly site.

Affected CPNs:

GBNG-09WNNA526_Affected_CPN_02192023.pdf GBNG-09WNNA526_Affected_CPN_02192023.csv

Notification Text:

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of G700LA as a new mold compound material for selected Atmel ATSENSE201 and ATSENSE301 device families available in 32L TQFP (7x7x1mm) package assembled at ASCL assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change				
Assembly Site	ASE Group Chung-Li	ASE Group Chung-Li				
	(ASCL)	(ASCL)				
Wire Material	PdCu	PdCu				
Die Attach Material	EN-4900GC	EN-4900GC				
Molding Compound Material	CEL-9240HF10AK	G700LA				
Lead Frame Material	C194	C194				

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change: To improve manufacturability by qualifying G700LA mold compound material.

Change Implementation Status: In Progress

Estimated First Ship Date: March 14, 2023 (date code: 2311)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	February 2022				February 2023				March 2023						
Workweek	0 6	0 7	08	09	10	>>	0 5	0 6	0 7	0 8	0 9	10	1 1	12	13
Initial PCN Issue Date		х													
Qual Report Availability										х					
Final PCN Issue Date										х					
Estimated Implementation Date													х		

Method to Identify Change: Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:February 11, 2022: Issued initial notification. February 19, 2023: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on March 14, 2023.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

GBNG-09WNNA526_Qual_Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. GBNG-09WNNA526 - CCB 5001 Final Notice: Qualification of G700LA as a new mold compound material for selected Atmel ATSENSE201 and ATSENSE301 device families available in 32L TQFP (7x7x1mm) package assembled at ASCL assembly site.

Affected Catalog Part Numbers (CPN)

ATSENSE301A-AU ATSENSE201HA-AU ATSENSE301HA-AU ATSENSE201A-AU ATSENSE301A-AN ATSENSE301A-ANR ATSENSE301A-AUR ATSENSE201HA-AUR ATSENSE201HA-AUR